

**Amendment and Response**

Applicant: Gerold Gruendler et al.

Serial No.: 10/598,285

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Docket No.: 1431.174.101/FIN565PCT/US

Title: COOLING SYSTEM FOR DEVICES HAVING POWER SEMICONDUCTORS AND METHOD FOR COOLING THE DEVICE

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**IN THE SPECIFICATION**

Please replace the paragraph beginning at Page 7, line 29 with the following rewritten paragraph:

The cooling air stream is generated by a cooling fan ~~(not shown)~~, such as illustrated by cooling fan CF, oriented such that the cooling air stream L flows parallel to the orientation of the printed circuit boards 4, 5 and 6. In order to increase the cooling effect of the cooling air stream L, the top side 15 of the cooling plates 11, 12 and 13 that is not in contact with the power semiconductor components 1, 2 and 3 may be equipped with cooling fins oriented parallel to the cooling air stream L, such as illustrated by cooling fins F.

Please replace the paragraph beginning at Page 8, line 1 with the following rewritten paragraph:

This cooling system 22 on the one hand has the advantage that it is not fixed to the power semiconductor component 1, 2 or 3 itself, and on the other hand has the advantage that the cooling effect can be intensified further by cooling plates that can be tilted toward one another being provided on both sides of the printed circuit boards 4, 5 and 6, such as illustrated by cooling plate 13' being positioned opposite cooling plate 13. This further solution is associated with the advantage that the printed circuit boards 4, 5 and 6 can be populated on both sides and the storage density of this memory unit can thus be increased further without thermally overloading the device.